

1 5. The gate stack structure as recited in Claim 1, wherein said refractory metal
2 silicide layer is tungsten silicide.

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4 6. The gate stack structure as recited in Claim 1, wherein said layer of doped
5 silicon dioxide layer is composed of a material selected from the group consisting of BPSG,
6 PSG, and BSG.

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8 7. The gate stack structure as recited in Claim 1, wherein the spacer is composed
9 of a material that is one of silicon nitride and undoped silicon dioxide.

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11 8. The gate stack structure as defined in Claim 1, wherein the first conductive
12 material is polysilicon.
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1 9. A gate stack structure situated over a base monocrystalline silicon layer, said
2 gate stack structure comprising:

3 a gate oxide layer on said base monocrystalline silicon layer;

4 a polysilicon gate layer on said gate oxide layer;

5 a layer of tungsten silicide on said polysilicon gate layer;

6 an undoped silicon dioxide cap on said layer of tungsten silicide;

7 a spacer over a lateral side of the gate layer and in contact with said base
8 monocrystalline silicon layer, said spacer being composed of undoped silicon dioxide
9 and being integral with the undoped silicon dioxide cap, wherein the lateral side of
10 the gate layer is oriented perpendicular to said base monocrystalline silicon layer;

11 a contact plug in contact with said base monocrystalline silicon layer and
12 being:

13 composed of a second conductive material; and

14 situated adjacent to the gate layer; and

15 a layer of doped silicon dioxide being composed of a material selected from
16 the group consisting of BPSG, PSG, and BSG, and being situated over said spacer,
17 over said undoped silicon dioxide cap, and in contact with said contact plug.

- 1 10. A gate stack structure situated over a base monocrystalline silicon layer, said
2 gate stack structure comprising:
3 a gate oxide layer on said base monocrystalline silicon layer;
4 a polysilicon gate layer on said gate oxide layer;
5 a layer of tungsten silicide on said polysilicon gate layer;
6 an undoped silicon dioxide cap on said layer of tungsten silicide;
7 a spacer over a lateral side of the gate layer and in contact with said base
8 monocrystalline silicon layer, said spacer being composed of of a material that is one
9 of silicon nitride and undoped silicon dioxide and being integral with the undoped
10 silicon dioxide cap, wherein the lateral side of the gate layer is oriented perpendicular
11 to said base monocrystalline silicon layer;
12 a contact plug in contact with said base monocrystalline silicon layer and
13 being:
14 composed of a second conductive material; and
15 situated adjacent to the gate layer; and
16 a layer of doped silicon dioxide being composed of a material selected from
17 the group consisting of BPSG, PSG, and BSG, and being situated over said spacer,
18 over said undoped silicon dioxide cap, and in contact with said contact plug.
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1 11. A gate structure comprising:

2 a pair of gate stacks situated over a base semiconductor material layer, each said gate
3 stack comprising:

4 a gate oxide layer on said base semiconductor material layer;

5 a gate layer, composed of a first conductive material, on said
6 gate oxide layer;

7 a layer of refractory metal silicide on said gate layer;

8 an undoped silicon dioxide cap on said layer of refractory
9 metal silicide; and

10 a spacer in contact with a lateral side of each said gate stack
11 and with said base semiconductor material layer, said spacer being
12 composed of a nonconductive material, each said lateral side of each
13 said gate stack being perpendicular to said base semiconductor
14 material layer;

15 a contact plug in contact with said base semiconductor material layer
16 composed of a second conductive material, and being situated between said pair of
17 gate stacks; and

18 a layer of doped silicon dioxide over said spacer, over said undoped silicon
19 dioxide cap, and in contact with said contact plug.

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21 12. A gate structure as recited in Claim 11, wherein said nonconductive material
22 is composed of silicon nitride.
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14 A process as recited in Claim 11, wherein the semiconductor material is

15 A process as recited in Claim 11, wherein said refractory metal silicide layer

16 A process as recited in Claims 11 wherein said layer of doped silicon dioxide

17 A process as recited in Claim 11 wherein the spacer is composed of a

18 / A gate structure as defined in Claim 11, wherein the first conductive material

a layer of doped silicon dioxide over said spacer, over said undoped silicon dioxide cap, and in contact with said contact plug.

20. A gate structure comprising:
a pair of gate stacks situated over a base monocrystalline silicon layer, each said gate stack comprising:
a gate oxide layer on said base monocrystalline silicon layer;
a polysilicon gate layer on said gate oxide layer;
a layer of tungsten silicide on said polysilicon gate layer;
an undoped silicon dioxide cap on said layer of tungsten silicide; and
a spacer over a lateral side of each said gate stack and in contact with said base monocrystalline silicon layer, said spacer being composed of a material that is one of silicon nitride and undoped silicon dioxide, each said lateral side of each said gate stack being perpendicular to said base monocrystalline silicon layer;
a contact plug in contact with said base monocrystalline silicon layer and being composed of a second conductive material, and being situated between said pair of gate stacks; and
a layer of doped silicon dioxide over said spacer, over said undoped silicon dioxide cap, and in contact with said contact plug.